

Terahertz technologies for specific applications

There are four main commercial terahertz (THz) technologies suitable for industrial use.

Time-domain spectroscopy

Time-domain spectroscopy (TDS) uses a pulsed THz signal activated by a laser.

The transmitter and receiver are fibre-coupled.

Achievable specifications (under optimal conditions):

- ▶ Bandwidth: 0.1-6 THz
- ▶ Frequency resolution:
 - ▶ 0.5 GHz using delay
 - ▶ 1.5 GHz using ECOPS
 - ▶ 100 MHz using ASOPS
- ▶ Spatial resolution: 250-1000 μm , depending on frequency
- ▶ Depth resolution: 5-10 μm

Frequency-modulated continuous wave

Frequency-modulated continuous wave (FMCW) uses a THz signal activated by a laser.

The transmitter and receiver are fibre-coupled.

Achievable specifications (under optimal conditions):

- ▶ Bandwidth: 0.1-4 THz
- ▶ Frequency resolution: 1 GHz
- ▶ Spatial resolution: 500-1000 μm , depending on frequency
- ▶ Depth resolution: 20 μm

Electronic FMCW operates at a fixed frequency up to 0.6 THz.

Continuous wave photonic-based frequency domain

Continuous wave photonic-based frequency domain (CW) uses a THz signal activated by a laser.

The transmitter and receiver are fibre-coupled.

Achievable specifications (under optimal conditions):

- ▶ Bandwidth: 0.05-3.2 THz
- ▶ Frequency resolution: 10 MHz
- ▶ Spatial resolution: 500-1000 μm , depending on frequency
- ▶ Depth resolution: N/A

Vector network analysis

Vector network analysis (VNA) uses a THz signal generated electronically.

The transmitter and receiver are waveguide-coupled in a rigid configuration.

Achievable specifications (under optimal conditions):

- ▶ Bandwidth: 0.01-1.2 THz
 - ▶ Note: Several sets of frequency extenders and waveguides are required to access the bandwidth.
 - ▶ Measurements are performed in waveguide-defined sub-octave bands.
- ▶ Frequency resolution: 1 MHz
- ▶ Spatial resolution: 2-5 mm, depending on frequency
- ▶ Depth resolution: N/A

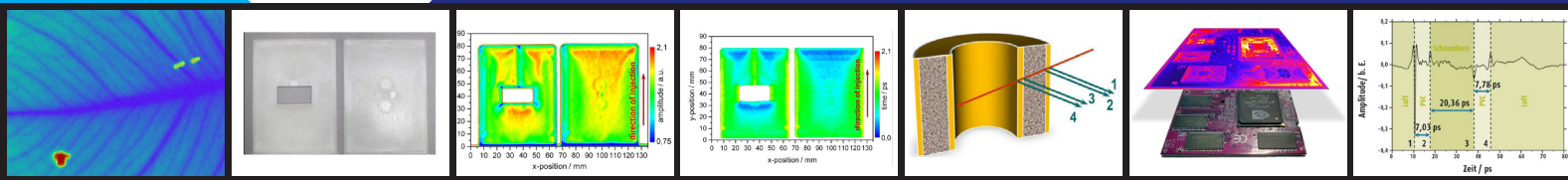


Table 1. Terahertz technologies suitable for various applications

Application	THz technology
Coatings monitoring and inspection <ul style="list-style-type: none"> ▶ Thickness of every layer in mono- and multilayer coatings ▶ Coating thickness uniformity ▶ Coating porosity ▶ Layer adhesion/delamination 	TDS FMCW
Conductivity and other electrical properties of thin films	TDS FMCW CW VNA
Corrosion/damage under coatings	TDS FMCW CW
Material inspection <ul style="list-style-type: none"> ▶ Complex permittivity ▶ Substance identification ▶ Porosity ▶ Moisture content ▶ Presence of contaminants 	TDS FMCW CW VNA
Imaging internal structures <ul style="list-style-type: none"> ▶ Layer thickness/uniformity ▶ Defects ▶ Voids ▶ Cracks and faults ▶ Debonding ▶ Delamination 	TDS FMCW
Trace gas sensing	CW VNA
Moisture content	TDS FMCW CW VNA

